

Notice of References Cited

Application/Control No.

09/756,971

Applicant(s)/Patent Under
Reexamination
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Examiner

David A. Zarneke

Art Unit

2827

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
*	U	Tummala et al., Microelectronics Packaging Handbook, Semiconductor Packaging - Part 11, 2nd Edition, 1997, Chapman & Hall, pages 898-901
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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